

Customer No.: 31561
Application No.: 10/065,632
Docket No.: 8012-US-PA

IN THE CLAIMS

Please amend the claims as follows.

Claims 1-14 (previously canceled)

15. (Currently Amended) A process for fabricating a bump, wherein the bump is disposed on a chip that has an active surface and at least a bonding pad, ~~and the bonding pad exposes the active surface~~, the process comprising:

forming a photoresist layer over the active surface of the chip, having at least an opening that exposes the bonding pad;

performing an activation step, for depositing a medium layer directly on the bonding pad in the opening of the photoresist layer; and

performing an electroless plating process for forming a conductive layer within the opening of the photoresist layer, so that at least a bump body is formed inside the opening and directly in contact with on the medium layer; and

removing the photoresist layer.

16. (Original) The process of claim 15, wherein a material of the bump body is nickel.

17. (Original) The process of claim 15, wherein a material of the medium layer is zinc.

Claim 18 (canceled).

19. (Original) The process of claim 15, after forming the bump body, further comprising forming a bump body passivation layer on the bump body covering the bump body except for a portion of the bump body that connects to the medium layer.

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20. (Original) The process of claim 19, wherein a material of the bump body passivation layer is gold.